

## PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT6116184

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
JIA SHI	05/13/2020
REZA SHERKAT	05/13/2020
JOHN SMIRNIOS	05/13/2020
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	SAP SE
<b>Street Address:</b>	DIETMAR-HOPP-ALLEE 16
<b>City:</b>	WALLDORF
<b>State/Country:</b>	GERMANY
<b>Postal Code:</b>	D-69190
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	16878419
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	(503)595-5301
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
<b>Phone:</b>	503-595-5300
<b>Email:</b>	ryan.heck@klarquist.com
<b>Correspondent Name:</b>	KLARQUIST SPARKMAN, LLP / RYAN A. HECK
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<b>Address Line 2:</b>	ONE WORLD TRADE CENTER
<b>Address Line 4:</b>	PORTALND, OREGON 97204
<b>ATTORNEY DOCKET NUMBER:</b>	8880-104234-01
<b>NAME OF SUBMITTER:</b>	RYAN A HECK
<b>SIGNATURE:</b>	/Ryan A. Heck/
<b>DATE SIGNED:</b>	05/20/2020
<b>Total Attachments: 3</b>	
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source=Assignment#page2.tif	
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Attorney Dkt. No. KS8880-104234-01 / 190825US01

**ASSIGNMENT**

For valuable consideration, I, **Ja Shi**,

hereby assign to

**SAP SE, a corporation of Europe having a place of business at Dietmar-Hopp-Allee 16, 69190 Walldorf, Germany**

and its successors, and assigns (collectively, the ASSIGNEE) my entire right, title and interest throughout the world in the inventions and improvements in a patent document entitled:

**Data Compression Techniques**

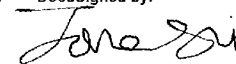
which is found in the:

US patent application filed on: May 19, 2020

under Application No. 16/878,419

I authorize and request the attorneys of record or the attorney filing the application to insert into this assignment the filing date and serial number of the application when known. This assignment includes the foregoing patent application or patent, as well as continuations and divisionals of said application, all legal equivalents in any country, and all patents issuing from such legal equivalents; all patents, utility models, and design registrations granted by any jurisdiction for any of said inventions and improvements; and the right to claim priority based on the filing date of the foregoing patent application or patent under the International Convention for the Protection of Industrial Property, the Patent Cooperation Treaty, the European Patent Convention, and all other treaties of like purposes. I authorize the Assignee to apply in all countries in my name or in its own name for patents, utility models, and design registrations and like rights of exclusion and for inventors' certificates for said inventions and improvements. I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into that would conflict with this assignment. I hereby state and agree that no assignment, sale, agreement, or encumbrance has been or will be made or entered into that would conflict with this assignment. I further agree for myself and my heirs, legal representatives, and assigns to provide to the Assignee promptly upon its request and at its expense all pertinent facts and documents relating to any of said inventions and improvements or said patents and legal equivalents as may be known and accessible to me and to testify as to the same in any interference, litigation, or proceeding relating thereto; and I agree promptly to perform such lawful acts and to sign such further applications, assignments, statements, and other lawful documents as the Assignee may reasonably request to effectuate fully this assignment.

Inventor's Signature:

DocuSigned by:  
  
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5/13/2020

**Ja Shi**

Attorney Dkt. No. KS8880-104234-01 / 190825US01

**ASSIGNMENT**

For valuable consideration, I, **Reza Sherkat**,  
hereby assign to

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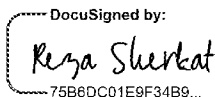
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5/13/2020

**Reza Sherkat**

Attorney Dkt. No. KS8880-104234-01 / 190825US01

**ASSIGNMENT**

For valuable consideration, I, **John Smirnios**,

hereby assign to

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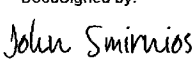
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5/13/2020

**John Smirnios**